

CDSV16-G

RoHS Device

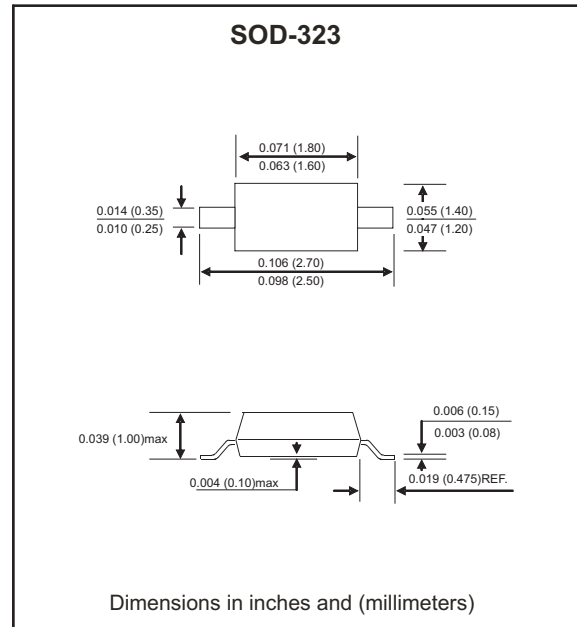


Features

- Fast Switching Speed
- Electrically Identical to Standard JEDEC
- High Conductance
- Surface Mount Package Ideally Suited for Automatic Insertion
- Flat Package SOD-123 in Stead mini-MELF Package

Mechanical data

- Case: SOD-323, Molded Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Weight: 0.01 gram(approx.)



Maximum Rating (at Ta=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Max	Unit
Non-Repetitive peak reverse voltage		V _{RM}		100	V
Peak repetitive peak reverse voltage Working peak reverse voltage DC blocking voltage		V _{RRM} V _{VRM} V _R		75	V
RMS reverse voltage		V _{R(RMS)}		53	V
Forward continuous current		I _{FM}		300	mA
Average rectified output current		I _o		150	mA
Peak forward surge current	T _P = 1μS T _P = 1S	I _{FSM}		2 1	A
Power dissipation		P _D		200	mW
Thermal Resistance (Junction to ambient)		R _{θJA}		625	°C/W
Storage temperature		T _{STG}	-65	+150	°C
Junction temperature		T _j		+125	°C

Electrical Characteristics (at Ta=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Forward voltage	I _F = 1 mA DC I _F = 10mA DC I _F = 50mA DC I _F = 150mA DC	V _F			0.715 0.855 1.0 1.25	V
Reverse current	V _R = 20 V V _R = 75 V	I _R			25 1	nA μA
Capacitance between terminals	f = 1 MHz, and 0VDC reverse voltage	C _T			2	pF
Reverse recovery time	I _F = I _R = 10 mA, R _L = 100 ohms, I _{rr} = 0.1 X I _R	T _{RR}			4	nS

Typical Characteristics (CDSV16-G)

Fig.1 - Forward Characteristics

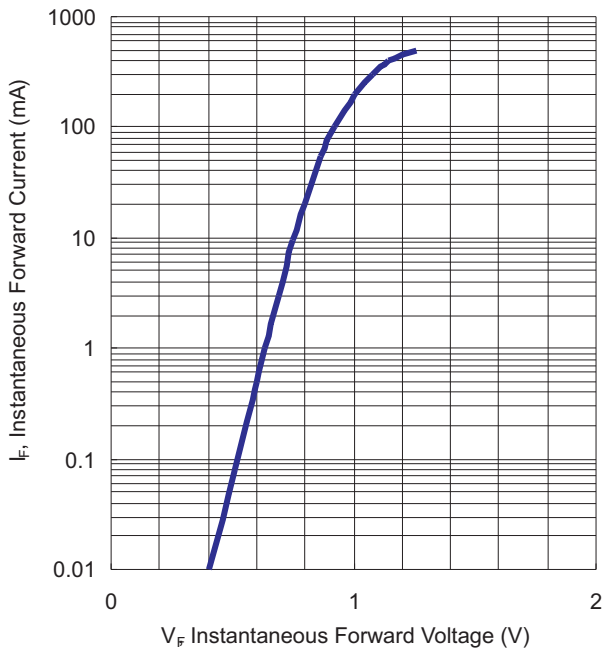


Fig.2 - Leakage current V.S. Junction Temperature

